

TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

TLGD175

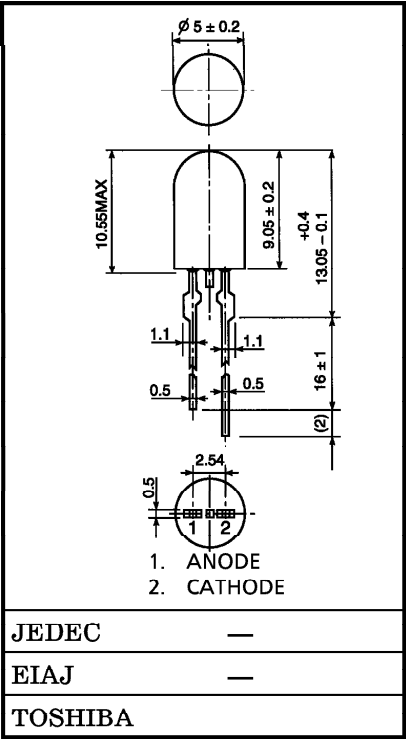
2 CHIP LED LAMP FOR MESSAGE BOARD

Unit in mm

- 2 Chip Series Connection
- All Plastic Mold Type : Clear Transparent Lens
- Low Drive Current, High Intensity Green Light Emission
Recommended Forward Current : $I_F = 15 \sim 20\text{mA}$ (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- Wide Radiation : Suitable for Message Board
($\pm 30\text{deg}$: //, $\pm 15\text{deg}$: $\perp$)

MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	I_F	30	mA
Reverse Voltage	V_R	8	V
Power Dissipation	P_D	120	mW
Operating Temperature Range	T_{opr}	$-30 \sim 85$	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	$-40 \sim 100$	$^\circ\text{C}$



Weight : 0.35g

ELECTRO-OPTICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V_F	$I_F = 20\text{mA}$	—	4.3	5.4	V
Reverse Current	I_R	$V_R = 8\text{V}$	—	—	5	μA
Luminous Intensity	I_V	$I_F = 20\text{mA}$ (Note)	153	400	—	mcd
			153	—	736	mcd
Peak Emission Wave Length	λ_p	$I_F = 20\text{mA}$	—	567	—	nm
Spectral Line Half Width	$\Delta\lambda$	$I_F = 20\text{mA}$	—	25	—	nm

(Note) Rank selection carried out under next standard range respectively, although it needs $\pm 15\%$ sdditionary for guaranteed limits.

P : 180-360mcd Q : 320-640mcd

Each rank products is classified by package unit, and (PQ) includes P and Q.

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PRECAUTION

Please be careful of the followings.

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
(Soldering portion of lead : below the lead stopper)
- If the lead is formed, the lead should be formed below the lead stopper without forming stress to the resin. Soldering should be performed after lead forming.

